

Further information on the 13<sup>th</sup> WIMNACT, including past history of WIMNACTs, can be found at the website:

[www.ntu.edu.sg/eee/eee6/conf/WIMNACT07.htm](http://www.ntu.edu.sg/eee/eee6/conf/WIMNACT07.htm)

Two of the DLs extended their stay in Singapore. Prof. Juin J. Liou gave a one-day short course on "Electrostatic Discharge (ESD) Protection in BiCMOS/CMOS Technology on 26<sup>th</sup> July and a day later on 27<sup>th</sup> July, Prof. Mansun Chan gave a talk on "IC Industry in China: Challenges and Opportunities".

This year, the Chapter's flagship conference on failure analysis, the International Symposium on the Physical and Failure Analysis of Integrated Circuits 2007, was held from 11-13 July in Bangalore, India. It was organized by IEEE ED/SSC Bangalore Chapter and co-sponsored by IEEE Rel/CPMT/ED Singapore Chapter. It comprised one day of tutorials and two days of Symposium and equipment exhibition. Full details can be found at:

[ewh.ieee.org/reg/10/ipfa/html/2007/index.htm](http://ewh.ieee.org/reg/10/ipfa/html/2007/index.htm)

Planning is now underway for IPFA 2008 which will be held in Singapore from 7<sup>th</sup> to 11<sup>th</sup> July 2008. The first call for papers has been issued and will be available on the Chapter website at [www.ewh.ieee.org/soc/cpmt/singapore/](http://www.ewh.ieee.org/soc/cpmt/singapore/)

Chapter's packaging conference, the 9th Electronics Packaging Technology Conference (EPTC 2007) will be held at Grand Copthorne Waterfront Hotel Singapore in Singapore from 10th to 12th December. Full details of EPTC can be found at the website: [eptc2007.confsof.org/](http://eptc2007.confsof.org/).

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## Newly Approved CPMT-Chapter in Austin

Submitted by Dr. Om P. Mandhana, Networking and Computing Systems Group, Freescale Semiconductor, Inc., Austin, Texas

A new CPMT Chapter in Austin, Texas is approved this year by the IEEE.

The first meeting of this Chapter was held on August 9, 2007 at Freescale Semiconductor, Austin, Texas.

The meeting was attended by many CPMT members from various industries in Austin, Texas area. Following office bearers for the CPMT-Austin Chapter were elected:

Chair: Om P. Mandhana, Freescale Semiconductor  
Treasurer: Jonathan Burnett, Freescale Semiconductor  
Technical Program Chair: Moises Cases, IBM  
Technical Program Co-Chair: Paul M. Harvey, IBM

Future monthly meetings of this Chapter will be held on Thursday of the first week.

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### Conference Reviews:

#### Conference report from HDP'07

Submitted by Dr. Johan Liu

SMIT Center, Chalmers University of Technology, Sweden,  
and Shanghai University & SHU-Intel Joint Lab, Shanghai  
University, China

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The 2007 International Symposium on High Density Packaging and Microsystem Integration (HDP'07) was success-

fully held from between 26 and June 28, 2007 in Shanghai, China. This year, the conference was co-located with the EU-China Green Electronics Workshop, an event that was sponsored by then European Commission and the Ministry of Science and Technology (MOST), China through the official 2007 Sino-EU Science Year Program.

The HDP'07 conference was sponsored by The Institute of Electrical and Electronics Engineers and Component, Packaging and Manufacture Technology Society and supported by The Ministry of Science and Technology and Shanghai Science and Technology Commission, Shanghai Municipal Government, China. We are very honored to have the welcome speeches by Mr. Jianfeng Lu, Principal Program Officer of Department of international collaboration, Shanghai Science and Technology Commission, Shanghai Government, Prof. Min Wang, Vice President of Shanghai University, Mr. Stefan Bengtsson, Vice President of Chalmers University of Technology, Sweden, and Mr. Lars Andresson, General Consul of the Consulate of Sweden in Shanghai. This conference was also supported by several media including China integrated circuit magazine, semiconductor technology magazine, semiconductor industry magazine and electronic assembly magazine.

More than 300 experts and researchers participated in the HDP'07 conference from countries and regions such as U.S.A., U.K., France, Sweden, Japan, India, Germany, Finland, Poland, Norway, Belgium, Korea, Hong Kong and Taiwan. More than 110 papers were presented in terms of oral and poster presentations. Moreover, we are honored to have outstanding keynote and invited speakers such as Prof. C.P. Wong, Member of Academy of engineers, USA, Fellow of IEEE, Prof. Georgia Tech, USA; Prof. James E. Morris, IEEE Fellow, Maseeh College of Engineering and Computer Science, Portland State University, USA; Prof K. Saganuma, Osaka University, Japan; Mr Matsuda, Hitachi Chemicals, Japan, Thomas Oppert, Pac-Tech, Germany; Dr. Tim Chen, General Manager of Henkel Electronics China Ltd; Dr. Dongkai Shangguan, Vice president, Flextronics U.S.A.; Michael, Todd, Technical Director, Henkel Electronics, USA; Dr. Fay Hua, Principal Engineer, Intel, USA; Dr. Daniel Lu, Staff Engineer, Intel Co., USA; Dr Guilian Gao, Tessera, USA; Dr. Ricky Lee, ASME Fellow, Hong Kong University of Science and Technology; Prof Michael Pecht, IEEE Fellow and Director of CALCE, University of Maryland, USA; Chris Bailey, Greenwich University, UK and Philip Pieters, IMEC, Belgium as well as well-known industries like Intel, Henkel, Huawei, Du Pont, Pac-Tech, Hirox, STS, Panasonic, Hitachi Chemical, Asymtek, Sang Yue, and universities such as Shanghai University, Tsing Hua University, Fudan University, Shanghai Jiaotong University, Huazhong University of Science and Technology, Central South University, Dalian University of Technology, Harbin Institute of Technology, Shanghai Institute of Microsystem and Information Technology, Chinese Academy Science, Hong Kong University of Science and Technology participating in the conference.

### Photos from HDP'07



For first time, there was an exhibition taken place during the conference. The following companies participated in the conference exhibition: Hitachi Chemicals, Panasonic, Henkel, STS, Hirox, Pac-Tech and Sang Yuen. Three best Intel student awards were to given to the students from Dalian University of Science and Technology, University of Science and Technology, Beijing and Hua Zhong University of Science and Technology, China. The HDP'07 conference provided an excellent opportunity for the microelectronics and microsystem industries to exchange the latest development in this fascinating field, especially with regard to the rapid growth of electronics industry in China.

In addition to this, three short courses were given by Prof. C.P. Wong, Prof. James Morris, Dr. Shangguan Dongkai, Dr. Fay Hua and Dr. Daniel Lu on nanotechnology as well as on lead free technology including solders and conductive adhesives.

### Workshop Reviews:

## Call for Participation in the 2007 IEEE/CPMT Workshop on Accelerated Stress Test and Reliability

Greenbelt Marriot in Greenbelt, Maryland  
October 31<sup>st</sup> through November 2<sup>nd</sup>, 2007  
Submitted by Kirk Gray, Dell Reliability Validation  
Engineer, Tel: 512-723-1374

This year's IEEE/CPMT Workshop on Accelerated Stress Test and Reliability Theme is: "Accelerated Life Testing, it's Role, Challenges, Attributes, and Interaction with Qualification Testing". Over the last few decades, Accelerated Stress Testing (AST) has been embraced by an ever widening array of worldwide companies seeking to reconcile the need for the highest quality product with the necessary push for early time-to-market. The purpose of the AST Workshop is to share ideas on better ways of accelerated testing, stress margin limit testing and analysis, and detecting hidden defects and weaknesses in electronic and electro-mechanical hardware that would result in failures. The goal of AST is to cost effectively develop mature robust products at market introduction.

You can access all the current Workshop information at our Website at [www.ewh.ieee.org/soc/cpmt/tc7/ast2007/](http://www.ewh.ieee.org/soc/cpmt/tc7/ast2007/)

Our registration page can be linked from the home page or accessed directly at URL:

[icm3.ieee.org/eventmanager/online/registration.asp?eventcode=9L6](http://icm3.ieee.org/eventmanager/online/registration.asp?eventcode=9L6)

Just some of the Presentations that are scheduled at this year's event:

Paul Parker	Power Supply Design and Test for Reliability
Ali Shakouri	Reliability and Testing on Nanostructure
Mike Silverman	Early Reliability Testing
Gary M. Hazard	Rapid Reliability Risk Assessment for Fiber Optic Components
Don Gerstle	Power Conversion Reliability

Hong S. Liu	Comparison Testing of Shock vs. Vibration ESS system
R.Zingher et al.	Enhancing Accelerated Life tests with monitoring and prognostication
Gustavo Plaza et al.	Study of Vibration Monitoring and Failure Criteria Definition for Solder Interconnect
Mike Silverman Hass	Profile Fine Tuning Using Field Data
David Francis	Case Study at CNH Case New Holland - HALT of Alternators
Koustav Sinha et al.	Mechanical strength of copper-silicon interface of planar metallization power modules
Gayatri Cuddalorepatta et al.	Durability Assessment of an Advanced Power Electronics Thermal Cooler
Jinsong Xie	A Case Study of Field Life Prediction and Reliability Assessment of Electronics Assemblies
Joey Bernstein et al.	Physics of Failure and Reliability Modeling of Electronic Packages

## 2008 IEEE Systems Packaging Japan Workshop

Hotel de YAMA, Hakone, Japan  
January 28 - 30, 2008

[www.ewh.ieee.org/soc/cpmt/tc14/](http://www.ewh.ieee.org/soc/cpmt/tc14/)

Submitted by Evan Davidson, Japanese Liaison for TCSP

### Call for Papers and Invitation

The Systems Packaging Japan Committee cordially invites you to participate in the 2008 IEEE Systems Packaging Japan Workshop (2008 SPJW), which will be held during January 28-30, 2008 at the Hotel de YAMA, Hakone, Japan. This workshop is held every other year in Japan and 2008 SPJW will be the twelfth one since the first workshop in 1986. State-of-the-art technologies in all areas of systems packaging from personal systems to high performance systems will be covered. Attendees are expected to be specialists in the field and to actively participate in all discussions. We look forward to meeting many of you at Hakone.

### Topics:

- IT Network Systems
- Digital Consumer Products & Mobile Information Systems
- High Performance Servers
- Advanced Packaging & Components
- Bio/Nano Technologies
- Environmental Aspects

For more information about the workshop, please feel free to contact Mr. Kishio Yokouchi, the Program Chair at:

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Fujitsu Interconnect Technologies Ltd.,  
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